

Sputter ATC 2200



It is a sputtering tool with the capability to co-sputter multiple material to obtain film with composition gradient on the depositing substrate

Location - Nano Lab

Capabilities

- Co- sputter 4 materials at a time.
- Deposition at elevated temperatures.
- Substrate to target distance variation possible.
- Angle of the gun can be varied.

Specifications

- No. of guns (targets) in the chamber – 7
- No. of RF sources – 3 (Max. 300 W)
- No. of DC sources – 1 (Max 750 W)
- No. of guns that can be used at the same time – 4 (3 RF & 1 DC)
- Max. substrate temperature – 600 °C
- Base Vacuum – 8×10^{-8} mTorr
- Deposition uniformity – 2 %
- Gases allowed – Ar, N₂

Target material , allowed substrates & materials

- http://www.cen.iitb.ac.in/cen/online_modules/equipmentdetail.php?machid=196